

# Searching PAJ

[MENU](#)[NEWS](#)[HELP](#)

Search Results : 31

[Index Indication](#)[Clear](#)[Text Search](#)

If you want to conduct a Number Search, please click on the button to the right.

[Number Search](#)

**Applicant, Title of invention, Abstract** — e.g. computer semiconductor

If you use the AND/OR operation, please leave a SPACE between keywords.

One letter word or Stopwords are not searchable.

[AND](#)

AND

[AND](#)

AND

[AND](#)

AND

**Date of publication of application** — e.g. 19980401 - 19980405

 - 

AND

**IPC** — e.g. D01B7/04 A01C11/02

If you use the OR operation, please leave a SPACE between keywords.

[Search](#)[Stored data](#)

Copyright (C); 1998,2003 Japan Patent Office

No.	Publication No.	Title
1.	<u>2003 - 276060</u>	INJECTION MOLDING DIE AND PIN THEREFOR
2.	<u>2003 - 136217</u>	EJECTION PIN FOR VACUUM DIE CASTING
3.	<u>2002 - 239707</u>	DIE CASTING APPARATUS
4.	<u>2001 - 200361</u>	OBSERVATORY APPARATUS IN HOT VACUUM VAPOR DEPOSITION APPARATUS
5.	<u>11 - 354616(1999)</u>	CHIP EJECTING DEVICE
6.	<u>11 - 026667(1999)</u>	MANUFACTURE OF SEMICONDUCTOR DEVICE
7.	<u>10 - 197700(1998)</u>	ELECTRON-BEAM IRRADIATION METHOD AND OBJECT IRRADIATED WITH ELECTRON BEAM
8.	<u>10 - 189511(1998)</u>	WAFER CLEANING DEVICE
9.	<u>10 - 048136(1998)</u>	METHOD AND APPARATUS FOR ANALYZING GAS ELEMENT
10.	<u>09 - 235676(1997)</u>	PLASMA TREATMENT AND PLASMA TREATING DEVICE
11.	<u>09 - 229563(1997)</u>	CASTING MACHINE
12.	<u>09 - 193174(1997)</u>	APPARATUS FOR EXTRACTING ELASTIC MOLDED PRODUCT AND METHOD
13.	<u>09 - 068808(1997)</u>	PHOTOCOMPOSING MACHINE
14.	<u>09 - 022665(1997)</u>	X-RAY IMAGE PICKUP TUBE AND MANUFACTURE THEREOF
15.	<u>07 - 316950(1995)</u>	EJECTION DEVICE FOR FLOAT WEFT
16.	<u>05 - 024080(1993)</u>	INJECTION MOLDING MOLD AND INJECTION MOLDING METHOD
17.	<u>04 - 336218(1992)</u>	MOLD
18.	<u>03 - 291389(1991)</u>	PLASMA TREATING DEVICE
19.	<u>03 - 254921(1991)</u>	INJECTION MOLD
20.	<u>03 - 254920(1991)</u>	INJECTION MOLD
21.	<u>03 - 161156(1991)</u>	VACUUM DIE CASTING MACHINE
22.	<u>02 - 258236(1990)</u>	MOLDING METHOD OF SHORT-FIBER-REINFORCED RESIN
23.	<u>01 - 320117(1989)</u>	SYNTHETIC RESIN MOLDING EQUIPMENT
24.	<u>01 - 109737(1989)</u>	CHUCKING DEVICE AND METHOD FOR REMOVING WAFER TO BE CUT OFF FROM LARGE DIE
25.	<u>63 - 264320(1988)</u>	METHOD AND APPARATUS FOR MOLDING DISC
26.	<u>63 - 210932(1988)</u>	COMPOSER
27.	<u>60 - 116421(1985)</u>	EXTRACTING DEVICE FOR MOLDED PART
28.	<u>58 - 197734(1983)</u>	MOLD PRODUCT LOADING/UNLOADING APPARATUS
29.	<u>58 - 059826(1983)</u>	RESIN CASING FOR VACUUM CLEANER OR THE LIKE

30. 57 - 160561(1982) VACUUM DIE CASTING METHOD

31. 57 - 160560(1982) PRESSURE CASTING DEVICE

Copyright (C); 1998,2003 Japan Patent Office

The screenshot shows a web browser window. The address bar at the top contains the text '1.jpg'. Below the address bar is a toolbar with four icons: a heart icon labeled 'Details', a document icon labeled 'Text', a camera icon labeled 'Image', and a document icon labeled 'HTML'. The main content area of the browser displays a large, pixelated image of a person's face, which appears to be a low-resolution scan or a heavily compressed image.

L Number	Hits	Search Text	DB	Time stamp
23	23	(vacuum suct\$3) adj nozzle with (resilient flexible) adj material	USPAT; EPO; JPO	2004/03/11 17:19
24	469	(vacuum suct\$3) adj nozzle with (resilient flexible rubber)	USPAT; EPO; JPO	2004/03/11 17:20
26	1	(vacuum suct\$3) adj (tip nozzle) with (resilient flexible rubber) and eject\$3 adj pin	USPAT; EPO; JPO	2004/03/11 17:21
27	1	(vacuum suct\$3) near (tip nozzle) with (resilient flexible rubber) and eject\$3 adj pin	USPAT; EPO; JPO	2004/03/11 17:21
28	12	(vacuum suct\$3) near (tip nozzle) with (resilient flexible rubber) and wafer	USPAT; EPO; JPO	2004/03/11 17:35
31	13	(vacuum suct\$3) near (tip nozzle) with (resilient flexible rubber) and die	USPAT; EPO; JPO	2004/03/11 17:36
32	603	(vacuum suct\$3) near (tip nozzle) with (resilient flexible rubber)	USPAT; EPO; JPO	2004/03/11 17:37
33	10	264/\$.ccls. and (vacuum suct\$3) near (tip nozzle) with (resilient flexible rubber)	USPAT; EPO; JPO	2004/03/11 17:37
34	21	29/\$.ccls. and (vacuum suct\$3) near (tip nozzle) with (resilient flexible rubber)	USPAT; EPO; JPO	2004/03/11 17:38
35	124	(vacuum suct\$3) near (tip nozzle) with rubber	USPAT; EPO; JPO	2004/03/11 17:44
36	76	(vacuum suct\$3) near (tip nozzle) with resilient	USPAT; EPO; JPO	2004/03/11 17:44
37	33	(vacuum suct\$3) near (tip nozzle) same resilient adj material	USPAT; EPO; JPO	2004/03/11 17:45
38	45	(vacuum suct\$3) near (tip nozzle) same flexible adj material	USPAT; EPO; JPO	2004/03/11 17:50
39	58	(vacuum suct\$3) near (tip nozzle) same (soft resilieant flexible) adj material	USPAT; EPO; JPO	2004/03/11 17:51
-	277	chen.in. and wafer.ti.	USPAT; US-PGPUB; EPO; JPO	2004/01/09 10:50
-	104	(chen.in. and wafer.ti.) and separat\$3 and semiconductor	USPAT; US-PGPUB; EPO; JPO	2004/01/09 10:51
-	4	((chen.in. and wafer.ti.) and separat\$3 and semiconductor) and tether	USPAT; US-PGPUB; EPO; JPO	2004/01/09 10:51
-	9	thin adj die same separat\$3 and vacuum	USPAT; EPO; JPO	2004/03/06 13:02
-	495	die same separat\$3 and vacuum same wafer	USPAT; EPO; JPO	2004/03/06 13:28
-	2	(die same separat\$3 and vacuum same wafer) and tether	USPAT; EPO; JPO	2004/03/06 13:04
-	62	(die same separat\$3 and vacuum same wafer) and clamp\$3 and moving	USPAT; EPO; JPO	2004/03/06 13:04
-	172	die same separat\$3 and vacuum and support same wafer and (clamp\$3 hold\$3) and (moving transfer\$3)	USPAT; EPO; JPO	2004/03/06 13:29
-	12	(die same separat\$3 and vacuum and support same wafer and (clamp\$3 hold\$3) and (moving transfer\$3)) and eject\$3 with pin	USPAT; EPO; JPO	2004/03/06 13:30
-	17	("1179482"   "2647578"   "3493155"   "3507426"   "3562057"   "3562058"   "3565306"   "3677875"   "3678550"   "3790051"   "4140260"   "4296542"   "4706370"   "4775085"   "5104023"   "5227001"   "5710065").PN.	USPAT	2004/03/10 11:26
-	4	wafer with die and vacuum and ejection adj pin	USPAT; EPO; JPO	2004/03/10 11:31
-	2	thin adj die and vacuum and ejection adj pin	USPAT; EPO; JPO	2004/03/10 11:32
-	32	position\$3 and clamp\$3 and moving and vacuum and ejection adj pin	USPAT; EPO; JPO	2004/03/10 11:35
-	0	downward with vacuum and ejection adj pin	USPAT; EPO; JPO	2004/03/10 11:35

-	0	down\$1ward with vacuum and ejection adj pin	USPAT; EPO; JPO	2004/03/10 11:35
-	1	breaking same vacuum and ejection adj pin	USPAT; EPO; JPO	2004/03/10 11:36
-	1	tether and vacuum and ejection adj pin	USPAT; EPO; JPO	2004/03/10 11:37
-	14	29/\$.ccls. and vacuum and ejection adj pin	USPAT; EPO; JPO	2004/03/10 11:38
-	11	257/\$.ccls. and vacuum and ejection adj pin	USPAT; EPO; JPO	2004/03/10 11:39
-	5	438/\$.ccls. and vacuum and ejection adj pin	USPAT; EPO; JPO	2004/03/10 11:40
-	12	(nozzle tip) with (suction vacuum) and ejection adj pin	USPAT; EPO; JPO	2004/03/10 11:40
-	50	4494902.URPN.	USPAT	2004/03/10 11:44
-	26	5169196.URPN.	USPAT	2004/03/10 13:31
-	9	("4667402"   "4859269"   "4874444"   "4990051"   "5169196"   "5351872"   "5447266"   "5589029"   "6201306").PN.	USPAT	2004/03/10 13:32
-	9	5960260.URPN.	USPAT	2004/03/10 13:36
-	6	("4664739"   "4793883"   "5194934"   "5237205"   "5444301"   "5504374").PN.	USPAT	2004/03/10 13:41
-	7	4876791.URPN.	USPAT	2004/03/10 13:41
-	14	("3632955"   "3902148"   "3946931"   "3949925"   "3958740"   "4010885"   "4135630"   "4151945"   "4166562"   "4270649"   "4372802"   "4498023"   "4500032"   "4510683").PN.	USPAT	2004/03/10 13:42
-	50	4494902.URPN.	USPAT	2004/03/10 13:45
-	6	("3274038"   "3785507"   "3793123"   "4290732"   "4375126"   "4410103").PN.	USPAT	2004/03/10 13:47
-	1	6205745.URPN.	USPAT	2004/03/10 13:48
-	3	("4494902"   "5203143"   "5319846").PN.	USPAT	2004/03/10 13:48
-	0	6190115.URPN.	USPAT	2004/03/10 13:48
-	3	("4494902"   "5310301"   "5348316").PN.	USPAT	2004/03/10 13:49
-	1	5966903.URPN.	USPAT	2004/03/10 13:49
-	3	("4494902"   "5203143"   "5319846").PN.	USPAT	2004/03/10 13:49
-	35	4740136.URPN.	USPAT	2004/03/10 13:50
-	2	("3906614"   "4494902").PN.	USPAT	2004/03/10 13:52
-	4	5589029.URPN.	USPAT	2004/03/10 13:52
-	3	("4850780"   "4859269"   "5348316").PN.	USPAT	2004/03/10 13:53
-	3	("4850780"   "4859269"   "5348316").PN.	USPAT	2004/03/10 13:53
-	21	4166562.URPN.	USPAT	2004/03/10 13:54
-	11	("3442432"   "3465408"   "3593404"   "3689991"   "3724068"   "3859718"   "3887783"   "3911568"   "3949925"   "4003125"   "4010885").PN.	USPAT	2004/03/10 13:56
-	18	3887783.URPN.	USPAT	2004/03/10 13:56
-	5	5120391.URPN.	USPAT	2004/03/10 13:59
-	5	("3937386"   "3941297"   "4050618"   "4166562"   "4526646").PN.	USPAT	2004/03/10 13:59

-	5	("4555876"   "4749329"   "4851902"   "4978253"   "5549716").PN.	USPAT	2004/03/10 14:00
-	3	5987722.URPN.	USPAT	2004/03/10 14:01
-	5	5120391.URPN.	USPAT	2004/03/10 14:02
-	8	5660318.URPN.	USPAT	2004/03/10 14:02
-	4	("4051508"   "4060828"   "4244002"   "5120391").PN.	USPAT	2004/03/10 14:03
-	4	("4051508"   "4060828"   "4244002"   "5120391").PN.	USPAT	2004/03/10 14:03
-	5	("3937386"   "3941297"   "4050618"   "4166562"   "4526646").PN.	USPAT	2004/03/10 14:03
-	124	separating and vacuum and eject\$3 adj pin	USPAT; EPO; JPO	2004/03/10 14:16
-	18	separating same wafer and (suction vacuum) and (push\$3 eject\$3) adj pin	USPAT; EPO; JPO	2004/03/10 14:19
-	62	(extract extracting separating) same (die chip ic) and (suction vacuum) and (push\$3 eject\$3) adj pin	USPAT; EPO; JPO	2004/03/10 14:20
-	3	("6297075"   "6337258"   "6429506").PN.	USPAT	2004/03/10 14:21
-	6	("5152707"   "5516125"   "5738165"   "5932065"   "5938211"   "6032715").PN.	USPAT	2004/03/10 14:21
-	1	6427539.pn.	USPAT; EPO; JPO	2004/03/10 16:31
-	0	6427539.URPN.	USPAT	2004/03/10 16:31
-	12	("3761784"   "4191057"   "4275406"   "4317126"   "4444054"   "4683755"   "4986861"   "4996627"   "5356176"   "5629486"   "5644102"   "5917264").PN.	USPAT	2004/03/10 16:31
-	42	4317126.URPN.	USPAT	2004/03/10 16:31
-	7	("3801949"   "3858150"   "4127840"   "4203327"   "4317126"   "4456901"   "4510671").PN.	USPAT	2004/03/10 16:32
-	9	4651120.URPN.	USPAT	2004/03/10 16:32
-	9	("3626096"   "3663768"   "3772133"   "3991285"   "4491697"   "4651120"   "4783821"   "4993072"   "5146435").PN.	USPAT	2004/03/10 16:33
-	10	5490220.URPN.	USPAT	2004/03/10 16:33
-	13	("2425481"   "3588382"   "4063050"   "4234811"   "4310906"   "4321432"   "4701640"   "4730283"   "5255246"   "5490220"   "5548658"   "6169810"   "6178249").PN.	USPAT	2004/03/10 16:34
-	0	6532293.URPN.	USPAT	2004/03/10 16:34
-	0	6532293.URPN.	USPAT	2004/03/10 16:34
-	10	5490220.URPN.	USPAT	2004/03/10 16:35
-	9	4651120.URPN.	USPAT	2004/03/10 16:35
-	7	("3801949"   "3858150"   "4127840"   "4203327"   "4317126"   "4456901"   "4510671").PN.	USPAT	2004/03/10 16:36
-	13	4275406.URPN.	USPAT	2004/03/10 16:36
-	6	("3758830"   "3761784"   "3893228"   "4125820"   "4131524"   "4204185").PN.	USPAT	2004/03/10 16:36